

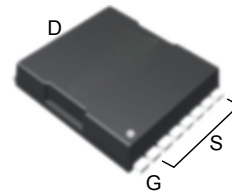
Features

- 40V/200A
 - $R_{DS(ON)}=1\text{m}\Omega(\text{typ.})@V_{GS}=10\text{V}$
 - $R_{DS(ON)}=1.4\text{m}\Omega(\text{typ.})@V_{GS}=4.5\text{V}$
- 100% UIS + R_g Tested
- Reliable and Rugged
- Lead Free and Green Devices Available (RoHS Compliant)
- Moisture Sensitivity Level MSL1 (per JEDEC J-STD-020D)

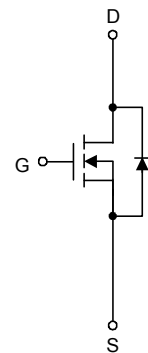
Applications

- SMPS Synchronous Rectification.
- Load Switch.
- DC-DC Conversion.

Pin Description



TO-LL



N-Channel MOSFET

Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ Unless Otherwise Noted)

Symbol	Parameter		Rating	Unit
Common Ratings				
V _{DSS}	Drain-Source Voltage		40	V
V _{GSS}	Gate-Source Voltage		±20	
T _J	Maximum Junction Temperature		150	°C
T _{STG}	Storage Temperature Range		-55 to 150	
I _S	Diode Continuous Forward Current	T _C =25°C	200	A
I _D	Continuous Drain Current	T _C =25°C	200	A
		T _C =100°C	120	
I _{DM} ^b	Pulsed Drain Current	T _C =25°C	380	
P _D	Maximum Power Dissipation	T _C =25°C	104	W
		T _C =100°C	42	
R _{θJC}	Thermal Resistance-Junction to Case	Steady state	1.2	°C/W
I _D	Continuous Drain Current	T _A =25°C	22.4	A
		T _A =70°C	18	
I _{DM} ^b	Pulsed Drain Current	T _C =25°C	90	
P _D	Maximum Power Dissipation	T _A =25°C	2.16	W
		T _A =70°C	1.38	
R _{θJA} ^c	Thermal Resistance-Junction to Ambient	t ≤ 10s	17	°C/W
		Steady state	58	
I _{AS} ^d	Avalanche Current, Single pulse	L=0.1mH	150	A
E _{AS} ^d	Avalanche Energy, Single pulse	L=0.1mH	1125	mJ

Note a : Max. continuous current is limited by bonding wire.

Note b : Pulse width limited by max. junction temperature.

Note c : Surface mounted on 1in^2 pad area, steady state $t = 999\text{s}$.

Note d : UIS tested and pulse width limited by maximum junction temperature 150°C (initial temperature $T_J=25^{\circ}\text{C}$).

Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

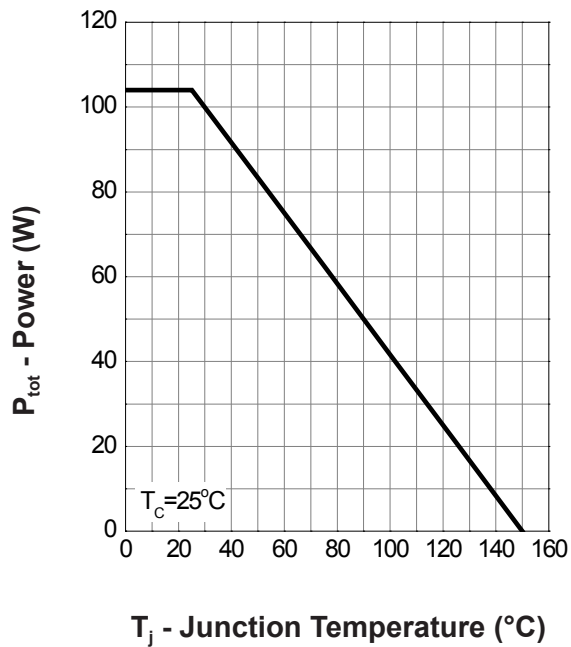
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250μA	40	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =32V, V _{GS} =0V T _J =85°C	-	-	1 30	μA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250μA	1.3	1.7	2.5	V
I _{GSS}	Gate Leakage Current	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
R _{DS(ON)} ^e	Drain-Source On-state Resistance	V _{GS} =10V, I _{DS} =25A T _J =125°C	-	1 2.2	1.5 -	mΩ
Gfs	Forward Transconductance	V _{DS} =5V, I _{DS} =15A	-	47	-	S
Diode Characteristics						
V _{SD} ^e	Diode Forward Voltage	I _{SD} =25A, V _{GS} =0V	-	0.8	1.1	V
t _{rr}	Reverse Recovery Time	I _{SD} =25A, dI _{SD} /dt=100A/μs	-	38	-	ns
t _a	Charge Time		-	23.8	-	
t _b	Discharge Time		-	14.2	-	
Q _{rr}	Reverse Recovery Charge		-	30	-	nC
Dynamic Characteristics ^f						
R _G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz	-	1	2	Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =20V, Frequency=1.0MHz	-	9500	10389	pF
C _{oss}	Output Capacitance		-	4500	-	
C _{rss}	Reverse Transfer Capacitance		-	3200	-	
t _{d(ON)}	Turn-on Delay Time	V _{DD} =20V, R _L =20Ω, I _{DS} =1A, V _{GEN} =10V, R _G =6Ω	-	18.3	33	ns
t _r	Turn-on Rise Time		-	10.3	19	
t _{d(OFF)}	Turn-off Delay Time		-	57.5	104	
t _f	Turn-off Fall Time		-	51.3	93	
Gate Charge Characteristics ^f						
Q _g	Total Gate Charge	V _{DS} =20V, V _{GS} =10V, I _{DS} =25A	-	50	70	nC
Q _g	Total Gate Charge	V _{DS} =20V, V _{GS} =4.5V, I _{DS} =25A	-	23	-	
Q _{gth}	Threshold Gate Charge		-	5.3	-	
Q _{gs}	Gate-Source Charge		-	9.6	-	
Q _{gd}	Gate-Drain Charge		-	6.7	-	

Note e : Pulse test ; pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.

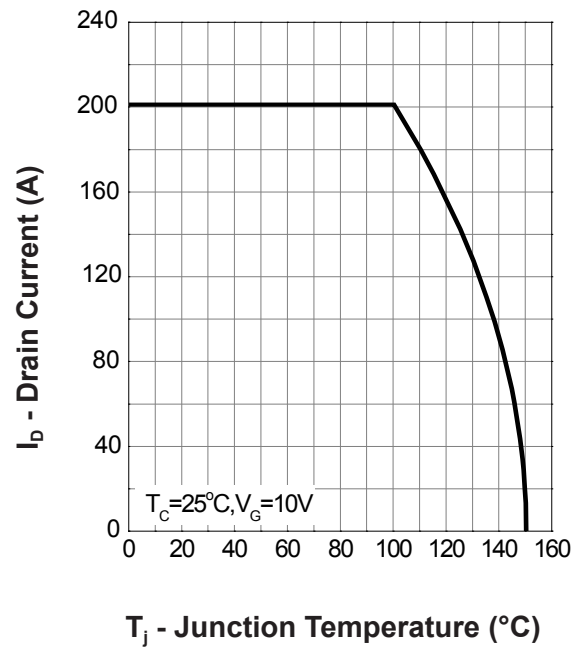
Note f : Guaranteed by design, not subject to production testing.

Typical Operating Characteristics

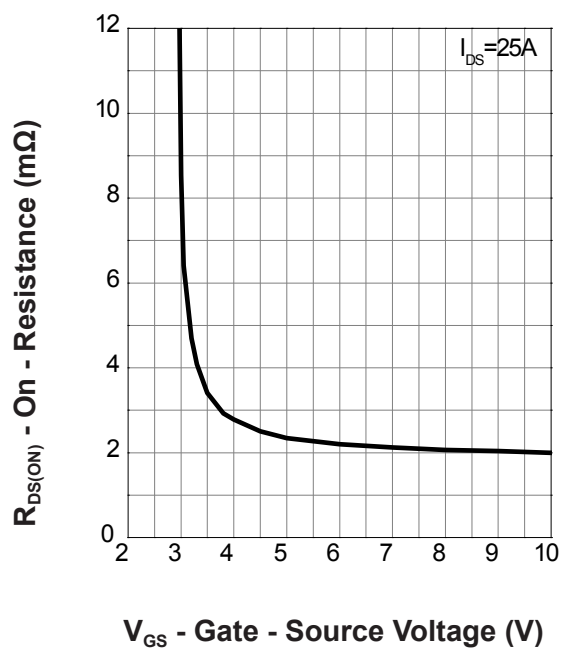
Power Dissipation



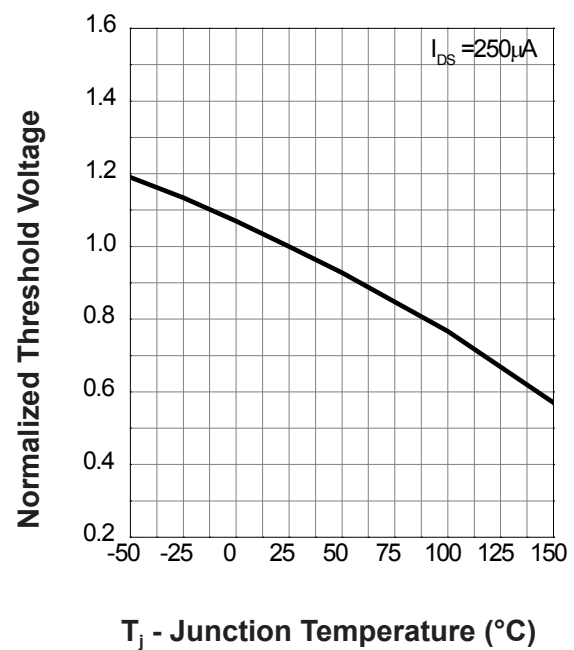
Drain Current



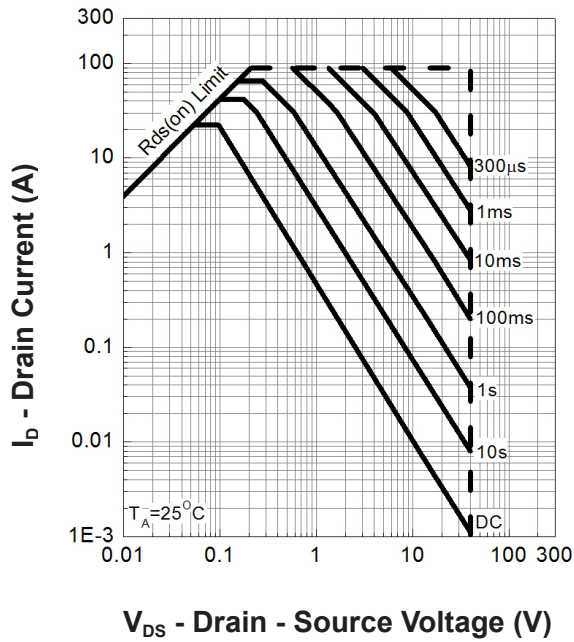
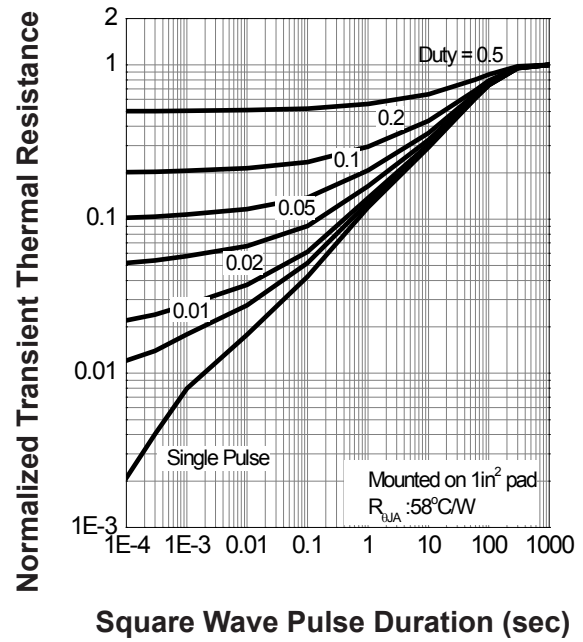
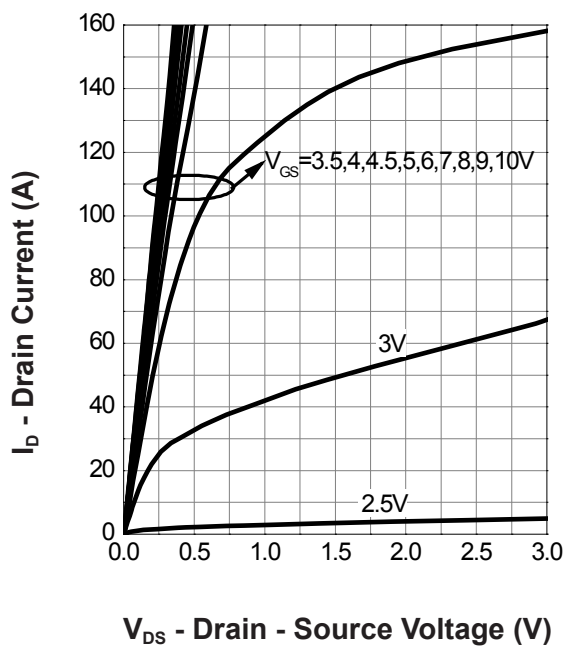
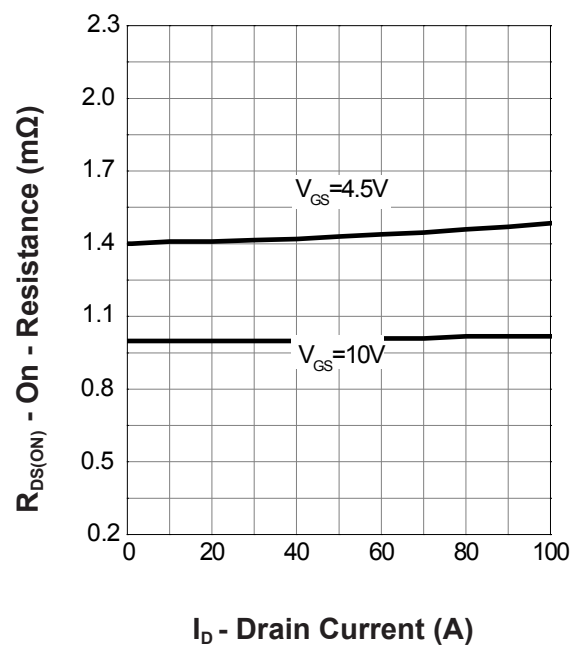
Gate-Source On Resistance



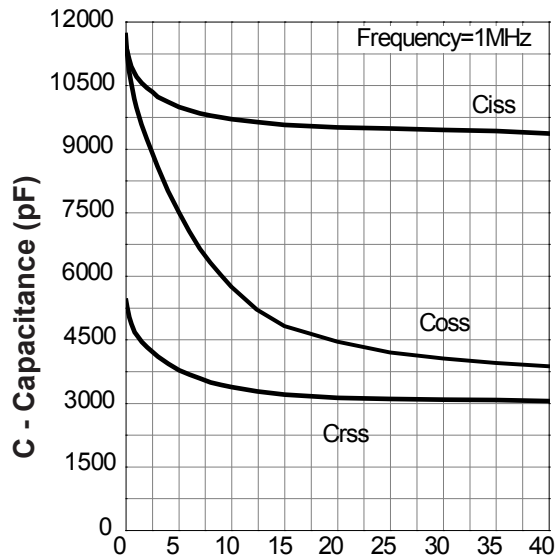
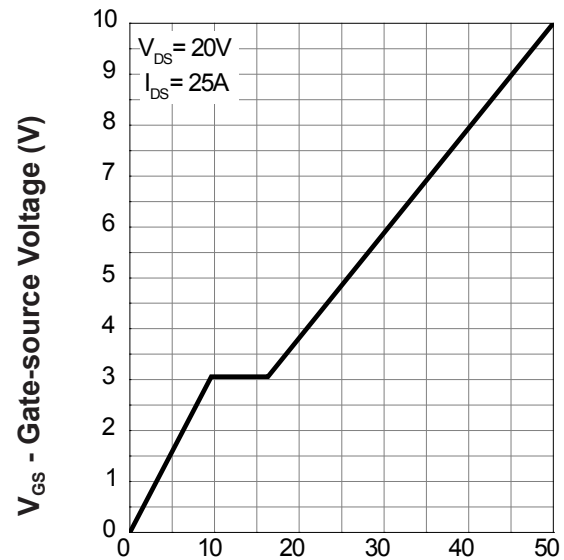
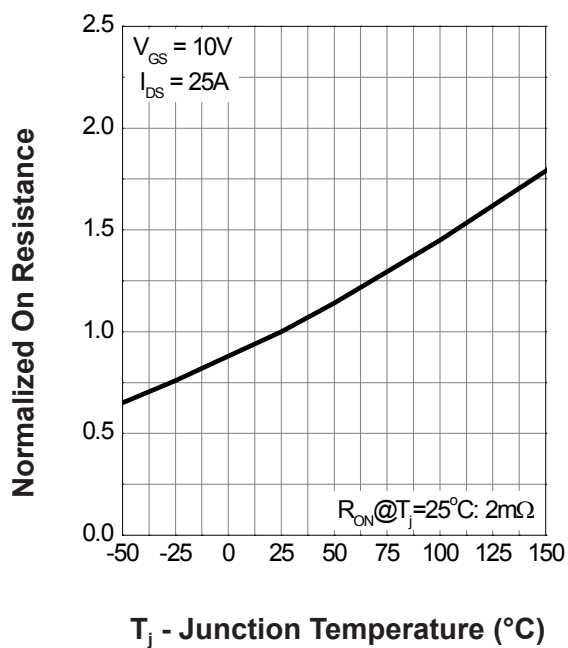
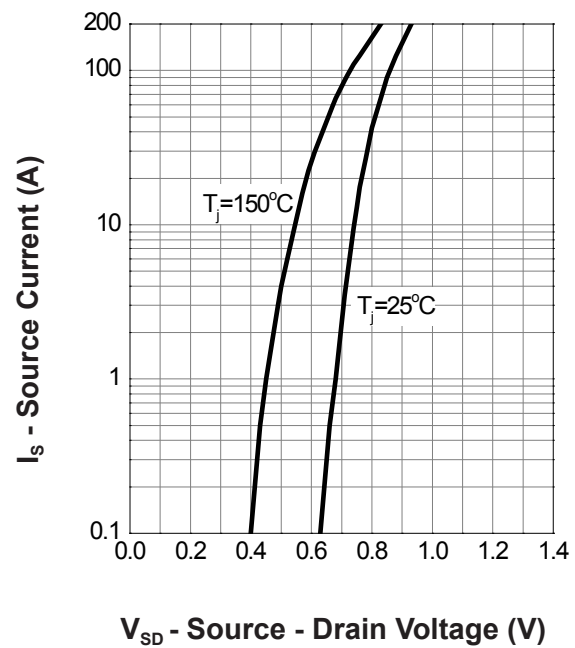
Gate Threshold Voltage



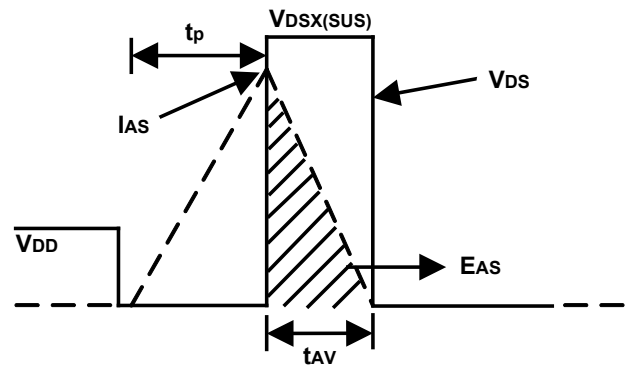
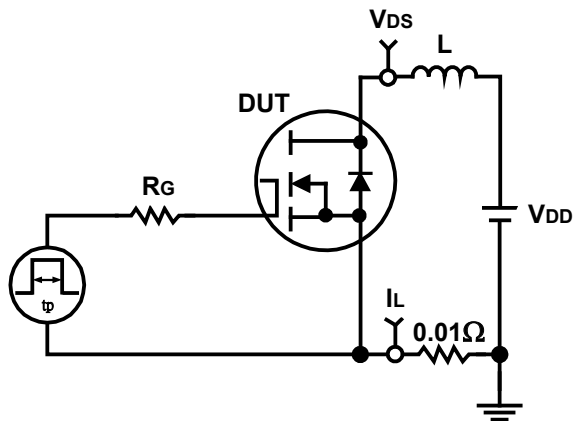
Typical Operating Characteristics(Cont.)

Safe Operation Area

Thermal Transient Impedance

Output Characteristics

Drain-Source On Resistance


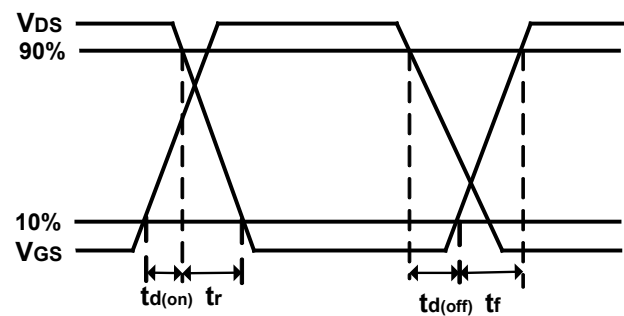
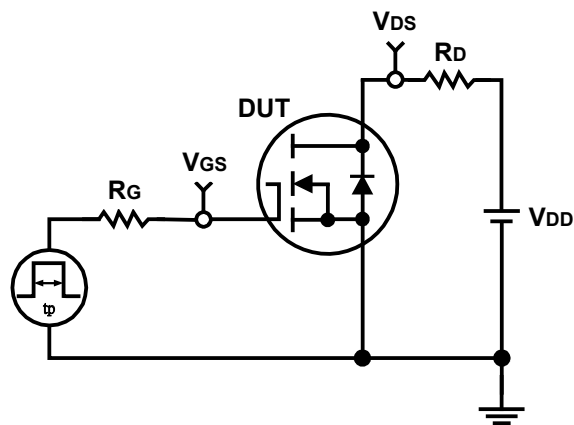
Typical Operating Characteristics(Cont.)

Capacitance

Gate Charge

Drain-Source On Resistance

Source-Drain Diode Forward


Avalanche Test Circuit and Waveforms

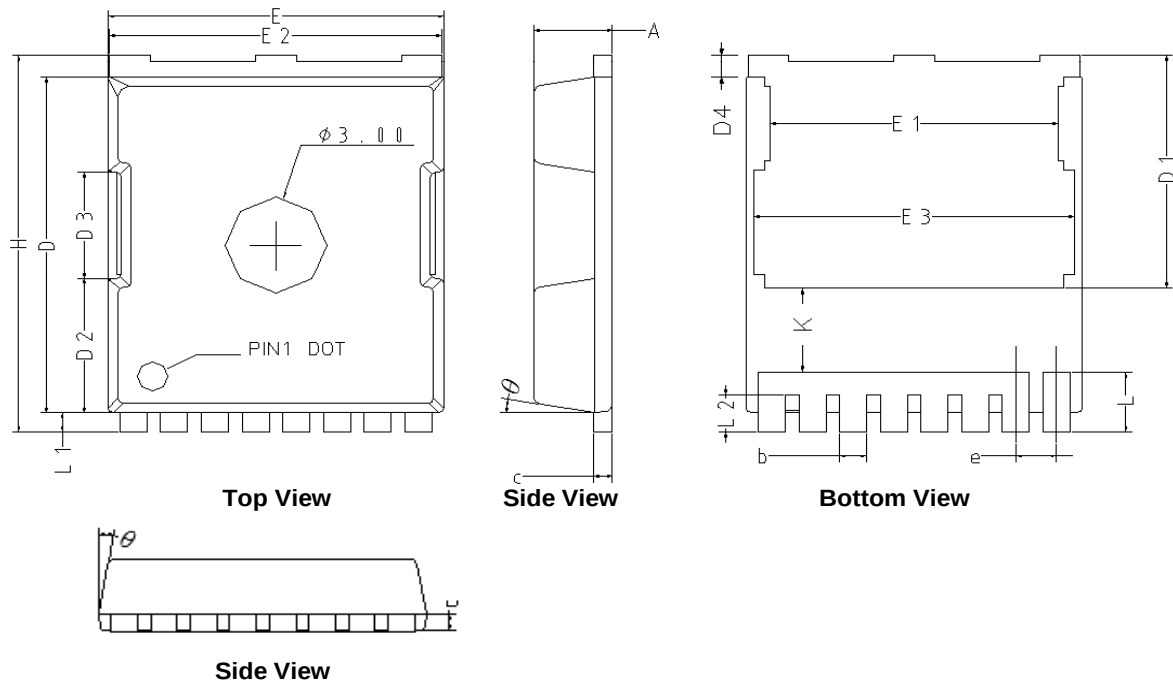


Switching Time Test Circuit and Waveforms



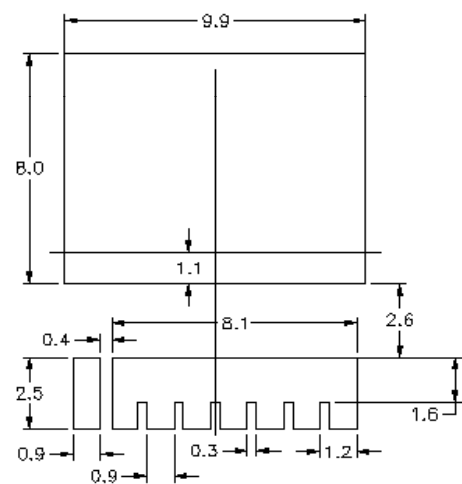
Package Information

TOLL



SYMBOLS	TO-LL			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	2.20	2.40	0.087	0.094
b	0.70	0.90	0.028	0.035
c	0.40	0.60	0.016	0.024
D	10.23	10.63	0.403	0.419
D1	7.05	7.45	0.278	0.293
D2	3.98	4.38	0.157	0.172
D3	3.10	3.50	0.122	0.138
D4	0.50	0.90	0.020	0.035
E	9.70	10.10	0.382	0.398
E1	8.30	8.70	0.327	0.343
E2	9.60	10.00	0.378	0.394
E3	9.26	9.66	0.365	0.380
H	11.53	11.93	0.454	0.470
e	1.2 BSC		0.0472 BSC	
K	2.43	2.83	0.096	0.111
L	1.65	2.05	0.065	0.081
L1	0.40	0.80	0.016	0.031
L2	0.95	1.35	0.037	0.053
θ	6°	10°	6°	10°

RECOMMENDED LAND PATTERN



UNIT: mm